

Fig. 2B is a cross-sectional view of the semiconductor module shown as mounted on the external heat sink according to another embodiment of the present invention wherein first and second metal plates of the mounting frame are shown to be of equal thickness;

Page 10, lines 6-13, please change the paragraph to read as follows:

Fig. 2A is a cross-sectional view of a semiconductor module 19 shown as mounted on the external heat sink 11 according to a second preferred embodiment of the present invention. The semiconductor module 19 comprises a double-layer structure including a lower metal plate 13a having a mounting surface for contact with the external heat sink 11 and an upper metal plate 13b secured on the lower metal plate 13a, in place of the metal frame 13 shown in Fig. 1. The inner periphery of the upper metal plate 13b projects inwardly from the inner periphery of the lower metal plate 13a to define a protrusion 21 corresponding to the flange 20 shown in Fig. 1.

Page 10, lines 14-20, please change the paragraph to read as follows:

The thickness of the lower metal plate 13a is equal to the sum of the thickness of the ceramic plate 1 and the thickness of the second metal plate 3. The upper metal plate 13b may be of any thickness, but is preferably as thick as the lower metal plate 13a, as shown in Fig. 2B, in consideration for the ease of manufacturing management. The remaining structure of the semiconductor module 19 according to the second preferred embodiment is identical with the corresponding structure of the semiconductor module 18 of the first preferred embodiment in Fig. 1.

Page 13, lines 19-25, please change the paragraph to read as follows: